



500.36904X00

RESPONSE UNDER RULE 1.116
EXPEDITED PROCEDURE
EXAMINING GROUP: 2814
BOX AF

#(A)
23E
1431/2

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: MIURA, et al.
Serial No.: 09/254,939
Filed: March 17, 1999
For: METHOD OF FABRICATING SEMICONDUCTOR DEVICE
HAVING TRENCH ELEMENT SEPARATION STRUCTURE
Group: 2814
Examiner: Anh D. Mai

AMENDMENT AFTER FINAL REJECTION

Assistant Commissioner for Patents
Washington, D.C. 20231
BOX AF

December 2, 2002

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Sir:

In response to the Office Action mailed July 30, 2002, please amend the
above-identified application as follows:

IN THE CLAIMS

Please cancel claims 14 and 40 without prejudice or disclaimer, and amend
the claims remaining in the application as follows:

1. (Four Times Amended) A method of fabricating a semiconductor
device comprising the steps of:
- (a) forming an oxidation prevention film on a circuit formation surface of a